

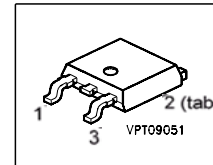
## Cool MOS™ Power Transistor

### Feature

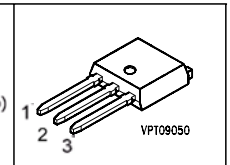
- New revolutionary high voltage technology
- Ultra low gate charge
- Periodic avalanche rated
- Extreme  $dv/dt$  rated
- Ultra low effective capacitances
- Improved transconductance
- Pb-free lead plating; RoHS compliant
- Qualified according to JEDEC<sup>0)</sup> for target applications

|                     |     |          |
|---------------------|-----|----------|
| $V_{DS} @ T_{jmax}$ | 650 | V        |
| $R_{DS(on)}$        | 6   | $\Omega$ |
| $I_D$               | 0.8 | A        |

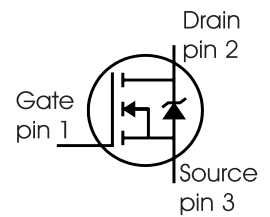
PG-TO252



PG-TO251



| Type       | Package  | Ordering Code | Marking |
|------------|----------|---------------|---------|
| SPU01N60C3 | PG-TO251 | Q67040-S4193  | 01N60C3 |
| SPD01N60C3 | PG-TO252 | Q67040-S4188  | 01N60C3 |



### Maximum Ratings

| Parameter                                                                                                                 | Symbol              | Value       | Unit             |
|---------------------------------------------------------------------------------------------------------------------------|---------------------|-------------|------------------|
| Continuous drain current<br>$T_C = 25\text{ }^\circ\text{C}$<br>$T_C = 100\text{ }^\circ\text{C}$                         | $I_D$               | 0.8<br>0.5  | A                |
| Pulsed drain current, $t_p$ limited by $T_{jmax}$                                                                         | $I_{D\text{ puls}}$ | 1.6         |                  |
| Avalanche energy, single pulse<br>$I_D = 0.6\text{ A}$ , $V_{DD} = 50\text{ V}$                                           | $E_{AS}$            | 20          | mJ               |
| Avalanche energy, repetitive $t_{AR}$ limited by $T_{jmax}$ <sup>1</sup><br>$I_D = 0.8\text{ A}$ , $V_{DD} = 50\text{ V}$ | $E_{AR}$            | 0.01        |                  |
| Avalanche current, repetitive $t_{AR}$ limited by $T_{jmax}$                                                              | $I_{AR}$            | 0.8         | A                |
| Gate source voltage static                                                                                                | $V_{GS}$            | $\pm 20$    | V                |
| Gate source voltage AC ( $f > 1\text{ Hz}$ )                                                                              | $V_{GS}$            | $\pm 30$    |                  |
| Power dissipation, $T_C = 25\text{ }^\circ\text{C}$                                                                       | $P_{tot}$           | 11          | W                |
| Operating and storage temperature                                                                                         | $T_j, T_{stg}$      | -55... +150 | $^\circ\text{C}$ |
| Reverse diode $dv/dt$ <sup>3)</sup>                                                                                       | $dv/dt$             | 15          | V/ns             |

**Maximum Ratings**

| Parameter                                                                                                           | Symbol  | Value | Unit |
|---------------------------------------------------------------------------------------------------------------------|---------|-------|------|
| Drain Source voltage slope<br>$V_{DS} = 480 \text{ V}$ , $I_D = 0.8 \text{ A}$ , $T_j = 125 \text{ }^\circ\text{C}$ | $dv/dt$ | 50    | V/ns |

**Thermal Characteristics**

| Parameter                                                         | Symbol     | Values |      |      | Unit             |
|-------------------------------------------------------------------|------------|--------|------|------|------------------|
|                                                                   |            | min.   | typ. | max. |                  |
| Thermal resistance, junction - case                               | $R_{thJC}$ | -      | -    | 11   | K/W              |
| Thermal resistance, junction - ambient, leaded                    | $R_{thJA}$ | -      | -    | 75   | K/W              |
| SMD version, device on PCB:<br>@ min. footprint                   | $R_{thJA}$ | -      | -    | 75   |                  |
| @ 6 cm <sup>2</sup> cooling area <sup>2)</sup>                    |            | -      | -    | 50   |                  |
| Soldering temperature, *)<br>1.6 mm (0.063 in.) from case for 10s | $T_{sold}$ | -      | -    | 260  | $^\circ\text{C}$ |

**Electrical Characteristics, at  $T_j=25^\circ\text{C}$  unless otherwise specified**

| Parameter                                   | Symbol        | Conditions                                                                                         | Values |             |         | Unit          |
|---------------------------------------------|---------------|----------------------------------------------------------------------------------------------------|--------|-------------|---------|---------------|
|                                             |               |                                                                                                    | min.   | typ.        | max.    |               |
| Drain-source breakdown voltage              | $V_{(BR)DSS}$ | $V_{GS}=0\text{V}$ , $I_D=0.25\text{mA}$                                                           | 600    | -           | -       | V             |
| Drain-Source avalanche<br>breakdown voltage | $V_{(BR)DS}$  | $V_{GS}=0\text{V}$ , $I_D=0.8\text{A}$                                                             | -      | 700         | -       |               |
| Gate threshold voltage                      | $V_{GS(th)}$  | $I_D=250\mu\text{A}$ , $V_{GS}=V_{DS}$                                                             | 2.1    | 3           | 3.9     |               |
| Zero gate voltage drain current             | $I_{DSS}$     | $V_{DS}=600\text{V}$ , $V_{GS}=0\text{V}$ ,<br>$T_j=25^\circ\text{C}$ ,<br>$T_j=150^\circ\text{C}$ | -<br>- | 0.1<br>-    | 1<br>50 | $\mu\text{A}$ |
| Gate-source leakage current                 | $I_{GSS}$     | $V_{GS}=30\text{V}$ , $V_{DS}=0\text{V}$                                                           | -      | -           | 100     |               |
| Drain-source on-state resistance            | $R_{DS(on)}$  | $V_{GS}=10\text{V}$ , $I_D=0.5\text{A}$ ,<br>$T_j=25^\circ\text{C}$<br>$T_j=150^\circ\text{C}$     | -<br>- | 5.6<br>15.1 | 6<br>-  | $\Omega$      |

\*) TO252: reflow soldering, MSL3; TO251: wavesoldering

**Electrical Characteristics** , at  $T_j = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

| Parameter                    | Symbol       | Conditions                                                                                    | Values |      |      | Unit |
|------------------------------|--------------|-----------------------------------------------------------------------------------------------|--------|------|------|------|
|                              |              |                                                                                               | min.   | typ. | max. |      |
| Transconductance             | $g_{fs}$     | $V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ ,<br>$I_D = 0.5\text{A}$                        | -      | 0.75 | -    | S    |
| Input capacitance            | $C_{iss}$    | $V_{GS} = 0\text{V}$ , $V_{DS} = 25\text{V}$ ,<br>$f = 1\text{MHz}$                           | -      | 100  | -    | pF   |
| Output capacitance           | $C_{oss}$    |                                                                                               | -      | 40   | -    |      |
| Reverse transfer capacitance | $C_{rss}$    |                                                                                               | -      | 2.5  | -    |      |
| Turn-on delay time           | $t_{d(on)}$  | $V_{DD} = 350\text{V}$ , $V_{GS} = 0/10\text{V}$ ,<br>$I_D = 0.8\text{A}$ , $R_G = 100\Omega$ | -      | 30   | -    | ns   |
| Rise time                    | $t_r$        |                                                                                               | -      | 25   | -    |      |
| Turn-off delay time          | $t_{d(off)}$ |                                                                                               | -      | 55   | 82   |      |
| Fall time                    | $t_f$        |                                                                                               | -      | 30   | 45   |      |

**Gate Charge Characteristics**

|                       |                 |                                                                                     |   |     |   |    |
|-----------------------|-----------------|-------------------------------------------------------------------------------------|---|-----|---|----|
| Gate to source charge | $Q_{gs}$        | $V_{DD} = 350\text{V}$ , $I_D = 0.8\text{A}$                                        | - | 0.9 | - | nC |
| Gate to drain charge  | $Q_{gd}$        |                                                                                     | - | 2.2 | - |    |
| Gate charge total     | $Q_g$           | $V_{DD} = 350\text{V}$ , $I_D = 0.8\text{A}$ ,<br>$V_{GS} = 0\text{ to }10\text{V}$ | - | 3.9 | 5 |    |
| Gate plateau voltage  | $V_{(plateau)}$ | $V_{DD} = 350\text{V}$ , $I_D = 0.8\text{A}$                                        | - | 5.5 | - | V  |

<sup>0</sup>J-STD20 and JESD22

<sup>1</sup>Repetitive avalanche causes additional power losses that can be calculated as  $P_{AV} = E_{AR} \cdot f$ .

<sup>2</sup>Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

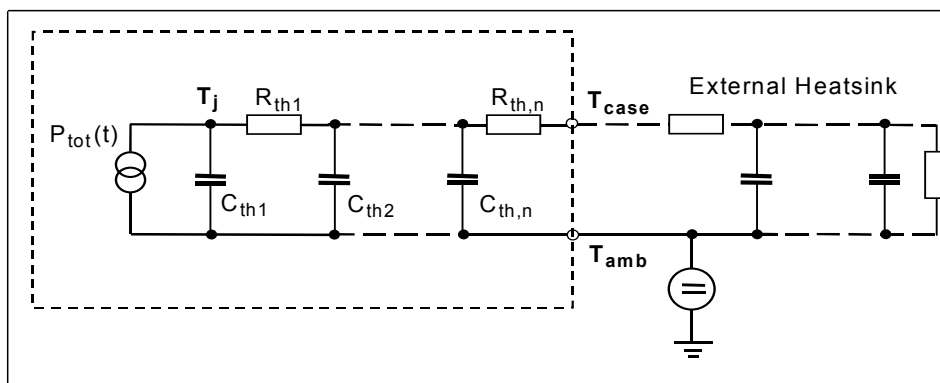
<sup>3</sup> $I_{SD} \leq I_D$ ,  $di/dt \leq 400\text{A}/\mu\text{s}$ ,  $V_{DClk} = 400\text{V}$ ,  $V_{peak} < V_{BR, DSS}$ ,  $T_j < T_{j,max}$ .  
 Identical low-side and high-side switch.

**Electrical Characteristics**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

| Parameter                                | Symbol   | Conditions                                                  | Values |      |      | Unit          |
|------------------------------------------|----------|-------------------------------------------------------------|--------|------|------|---------------|
|                                          |          |                                                             | min.   | typ. | max. |               |
| Inverse diode continuous forward current | $I_S$    | $T_C=25^\circ\text{C}$                                      | -      | -    | 0.8  | A             |
| Inverse diode direct current, pulsed     | $I_{SM}$ |                                                             | -      | -    | 1.6  |               |
| Inverse diode forward voltage            | $V_{SD}$ | $V_{GS}=0\text{V}, I_F=I_S$                                 | -      | 1    | 1.2  | V             |
| Reverse recovery time                    | $t_{rr}$ | $V_R=350\text{V}, I_F=I_S, di_F/dt=100\text{A}/\mu\text{s}$ | -      | 570  | 970  | ns            |
| Reverse recovery charge                  | $Q_{rr}$ |                                                             | -      | 0.75 | -    | $\mu\text{C}$ |

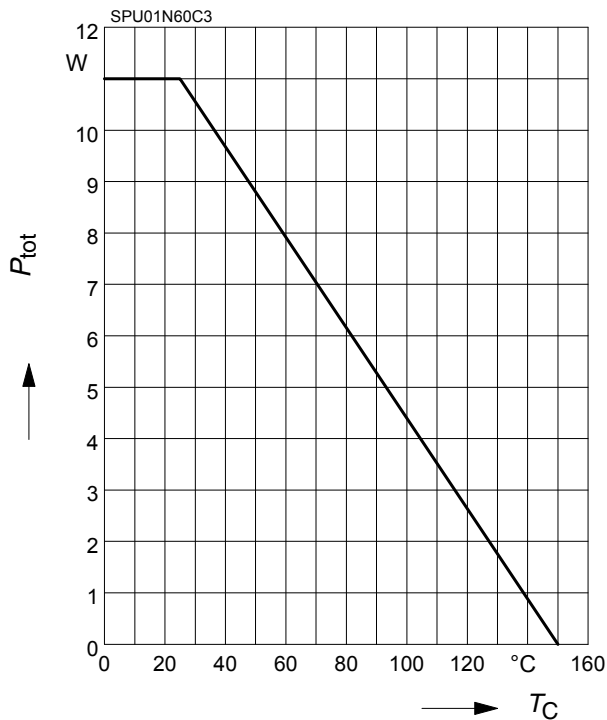
### Typical Transient Thermal Characteristics

| Symbol             | Value | Unit | Symbol              | Value      | Unit |
|--------------------|-------|------|---------------------|------------|------|
|                    | typ.  |      |                     | typ.       |      |
| Thermal resistance |       |      | Thermal capacitance |            |      |
| $R_{th1}$          | 0.225 | K/W  | $C_{th1}$           | 0.00001221 | Ws/K |
| $R_{th2}$          | 0.395 |      | $C_{th2}$           | 0.00005037 |      |
| $R_{th3}$          | 0.603 |      | $C_{th3}$           | 0.0000809  |      |
| $R_{th4}$          | 0.995 |      | $C_{th4}$           | 0.0002915  |      |
| $R_{th5}$          | 0.691 |      | $C_{th5}$           | 0.001844   |      |
| $R_{th6}$          | 0.148 |      | $C_{th6}$           | 0.412      |      |



### 1 Power dissipation

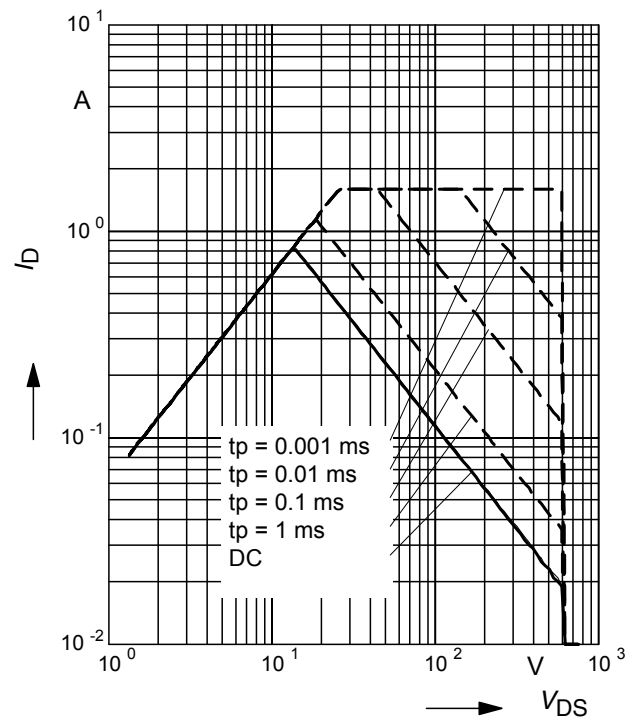
$$P_{\text{tot}} = f(T_C)$$



### 2 Safe operating area

$$I_D = f(V_{DS})$$

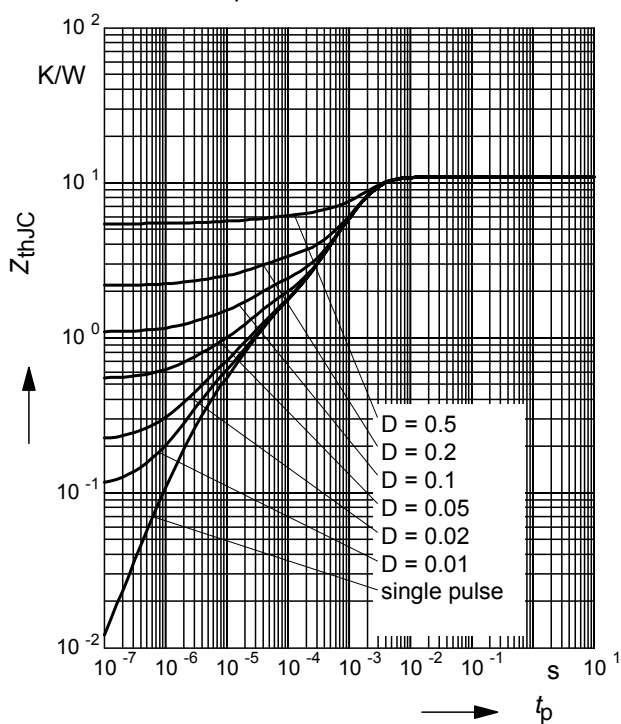
parameter:  $D = 0$ ,  $T_C = 25^\circ\text{C}$



### 3 Transient thermal impedance

$$Z_{\text{thJC}} = f(t_p)$$

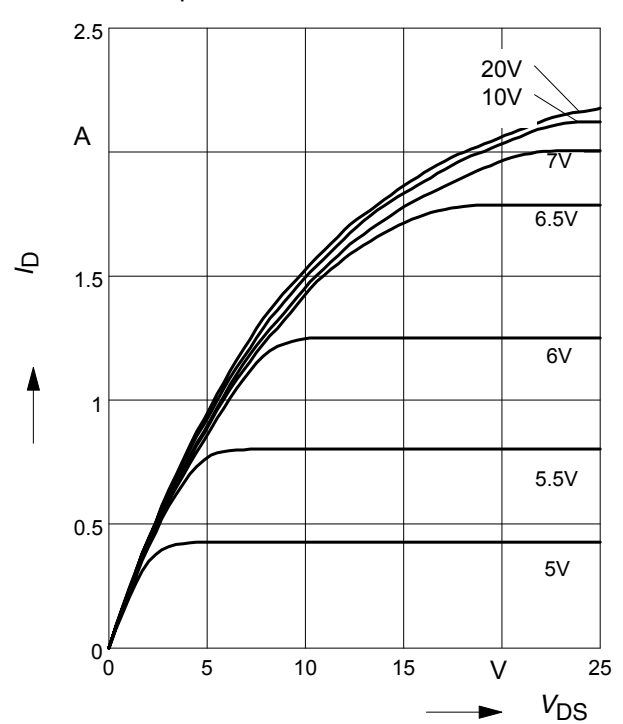
parameter:  $D = t_p/T$



### 4 Typ. output characteristic

$$I_D = f(V_{DS}); T_J = 25^\circ\text{C}$$

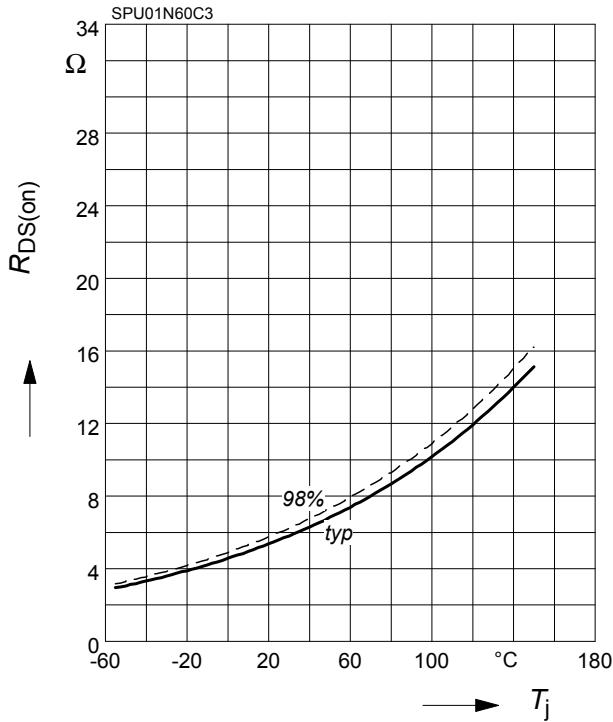
parameter:  $t_p = 10 \mu\text{s}$ ,  $V_{GS}$



## 5 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

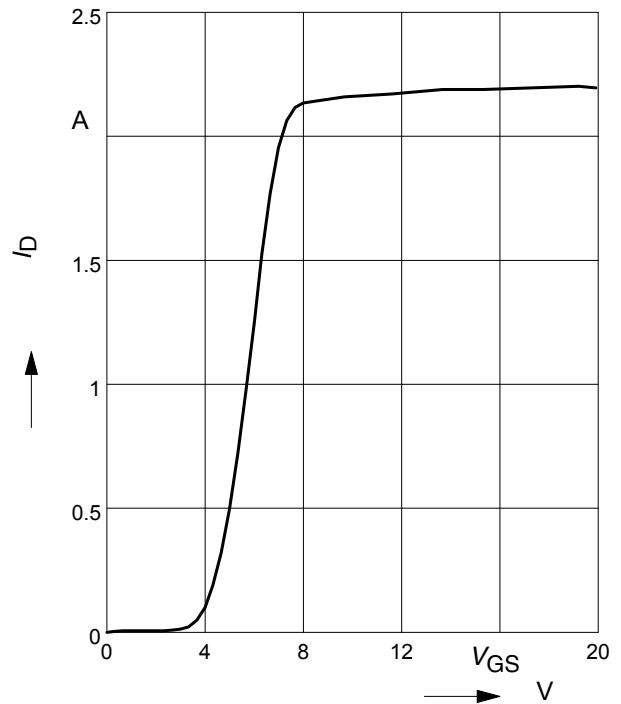
parameter:  $I_D = 0.5 \text{ A}$ ,  $V_{GS} = 10 \text{ V}$



## 6 Typ. transfer characteristics

$$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$$

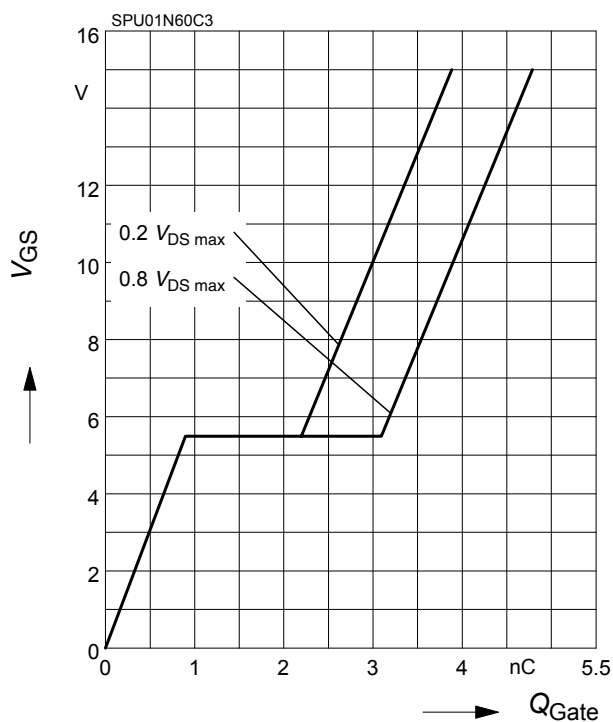
parameter:  $t_p = 10 \mu\text{s}$



## 7 Typ. gate charge

$$V_{GS} = f(Q_{Gate})$$

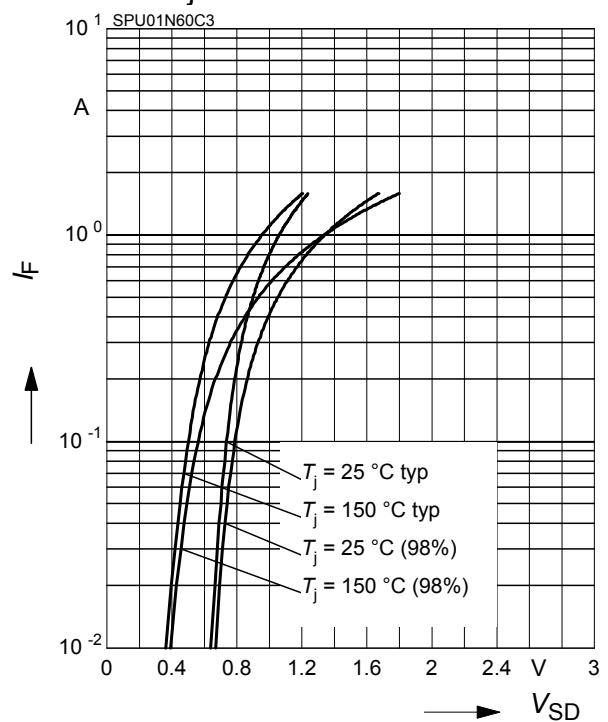
parameter:  $I_D = 0.8 \text{ A}$  pulsed



## 8 Forward characteristics of body diode

$$I_F = f(V_{SD})$$

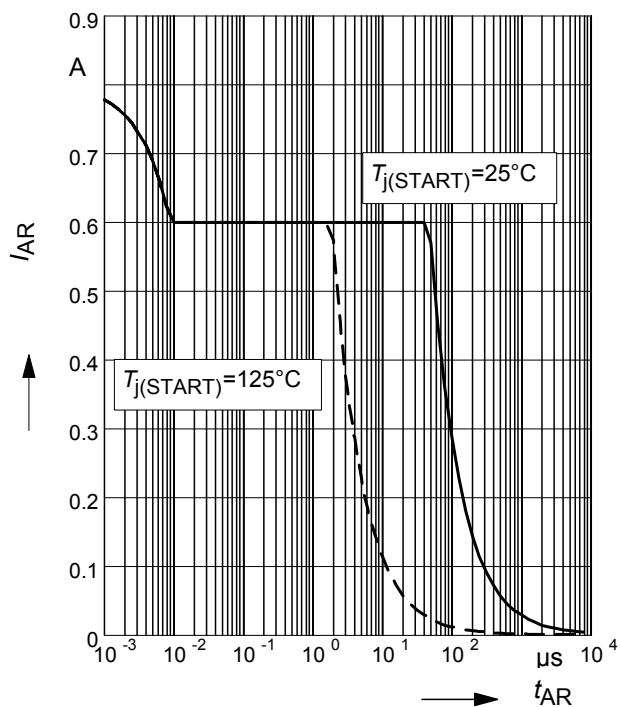
parameter:  $T_j$ ,  $t_p = 10 \mu\text{s}$



## 9 Avalanche SOA

$$I_{AR} = f(t_{AR})$$

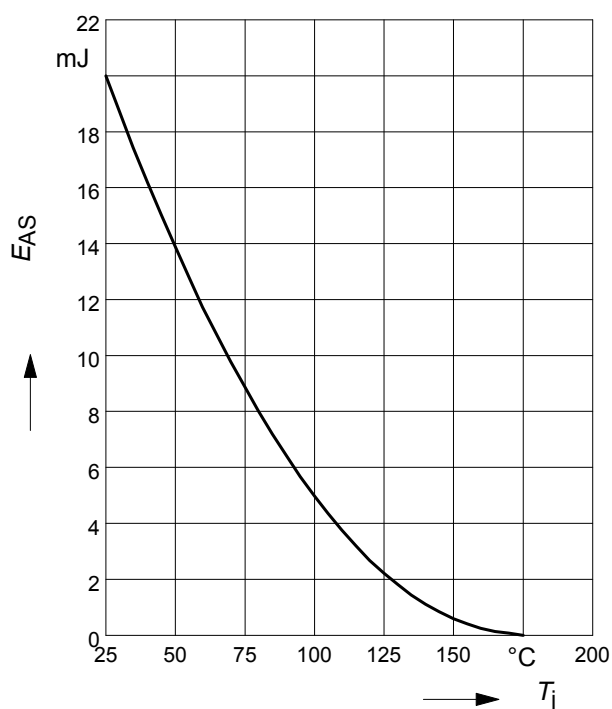
par.:  $T_j \leq 150^\circ\text{C}$



## 10 Avalanche energy

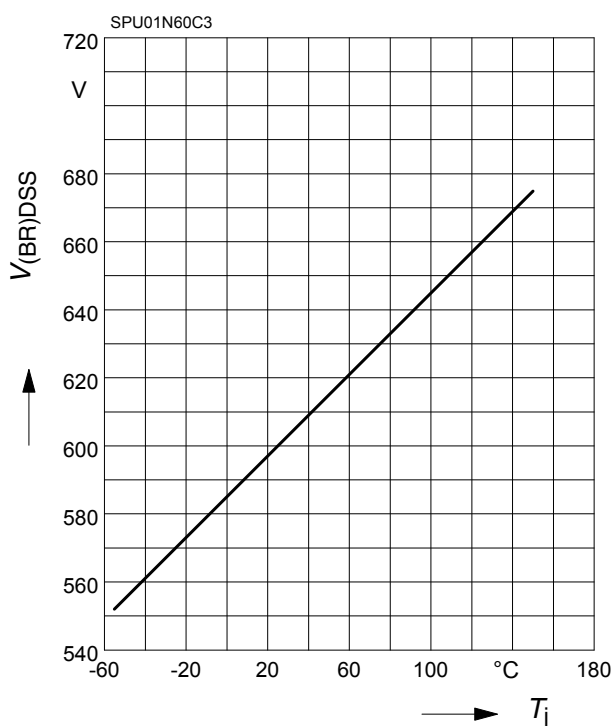
$$E_{AS} = f(T_j)$$

par.:  $I_D = 0.6\text{ A}$ ,  $V_{DD} = 50\text{ V}$



## 11 Drain-source breakdown voltage

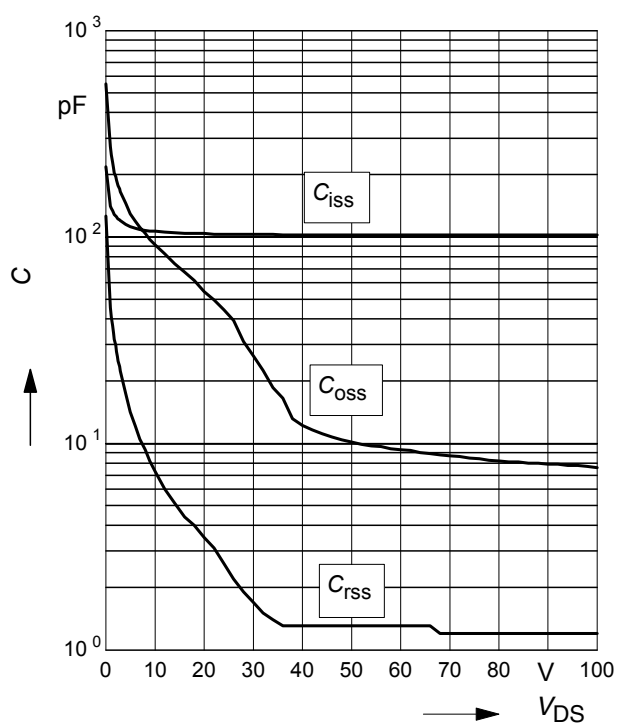
$$V_{(BR)DSS} = f(T_j)$$



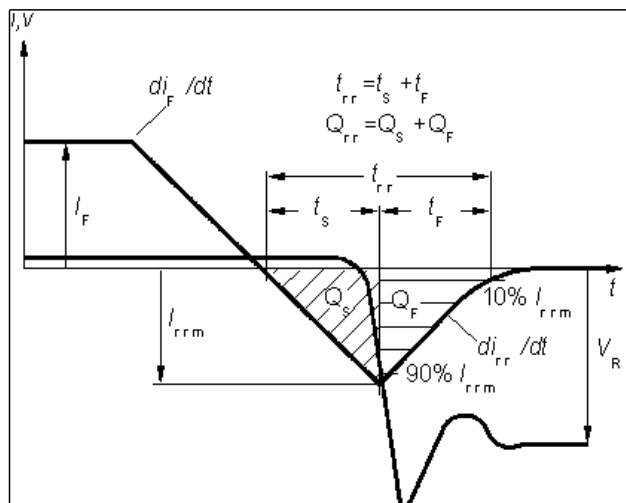
## 12 Typ. capacitances

$$C = f(V_{DS})$$

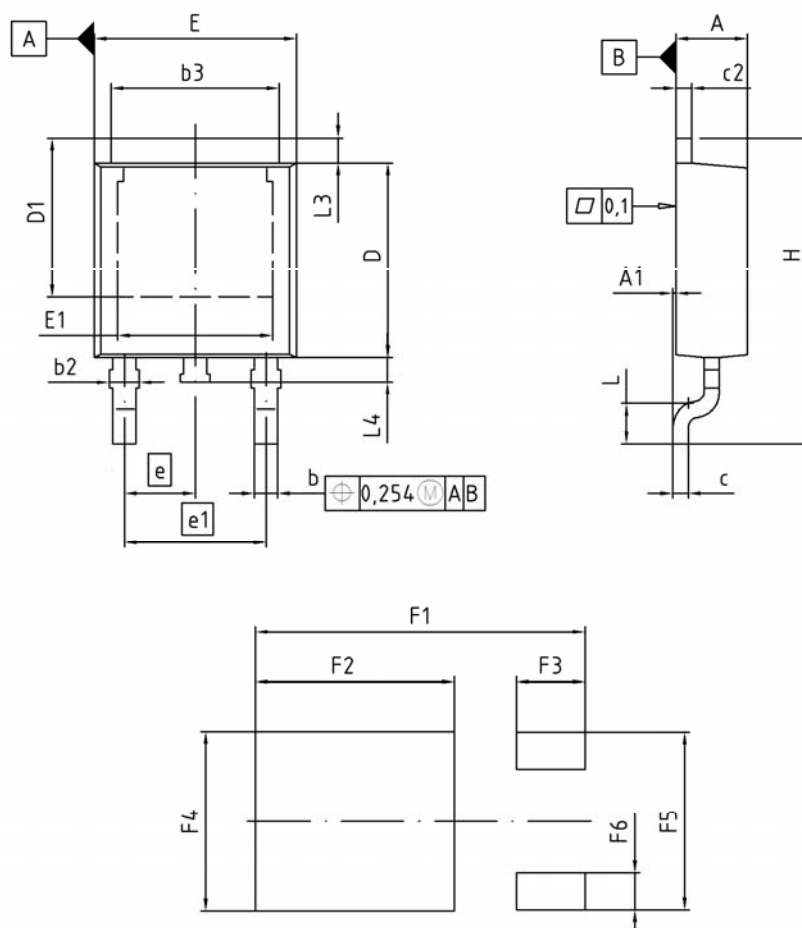
parameter:  $V_{GS} = 0\text{ V}$ ,  $f = 1\text{ MHz}$



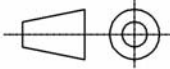
## Definition of diodes switching characteristics



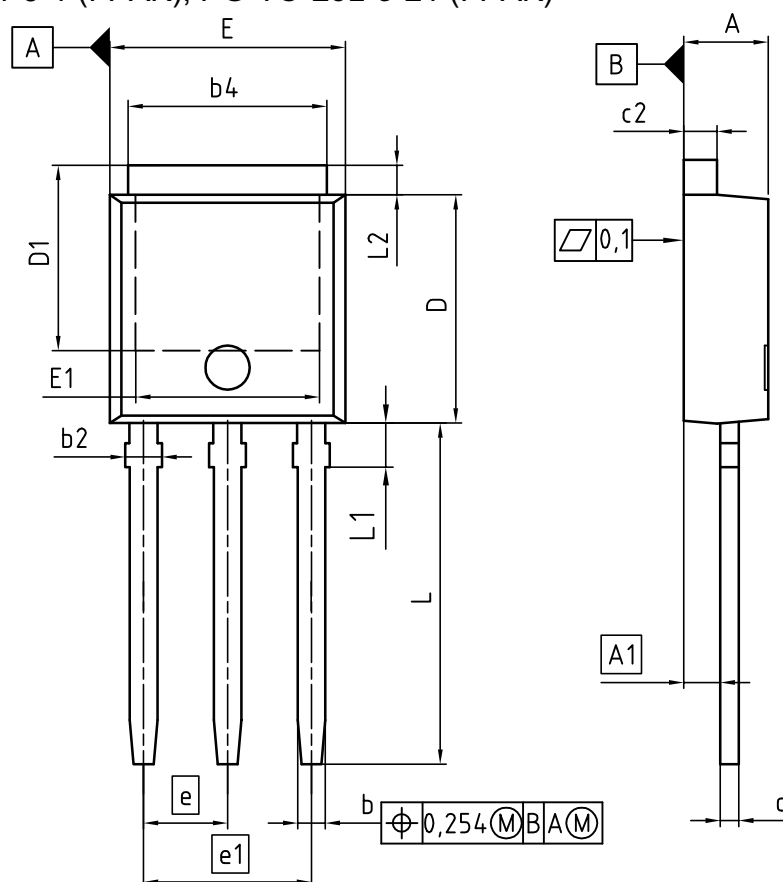
PG-TO-252-3-1 (D-PAK), PG-TO-252-3-11 (D-PAK), PG-TO-252-3-21 (D-PAK)



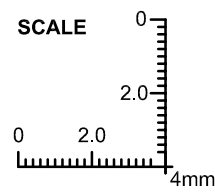
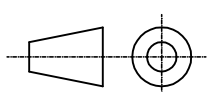
| DIM | MILLIMETERS |       | INCHES |       |
|-----|-------------|-------|--------|-------|
|     | MIN         | MAX   | MIN    | MAX   |
| A   | 2.16        | 2.41  | 0.085  | 0.095 |
| A1  | 0.00        | 0.15  | 0.000  | 0.006 |
| b   | 0.64        | 0.89  | 0.025  | 0.035 |
| b2  | 0.65        | 1.15  | 0.026  | 0.045 |
| b3  | 5.00        | 5.50  | 0.197  | 0.217 |
| c   | 0.46        | 0.60  | 0.018  | 0.024 |
| c2  | 0.46        | 0.98  | 0.018  | 0.039 |
| D   | 5.97        | 6.22  | 0.235  | 0.245 |
| D1  | 5.02        | 5.84  | 0.198  | 0.230 |
| E   | 6.40        | 6.73  | 0.252  | 0.265 |
| E1  | 4.70        | 5.21  | 0.185  | 0.205 |
| e   | 2.29        |       | 0.090  |       |
| e1  | 4.57        |       | 0.180  |       |
| N   | 3           |       | 3      |       |
| H   | 9.40        | 10.48 | 0.370  | 0.413 |
| L   | 1.18        | 1.70  | 0.046  | 0.067 |
| L3  | 0.90        | 1.25  | 0.035  | 0.049 |
| L4  | 0.51        | 1.00  | 0.020  | 0.039 |
| F1  | 10.50       | 10.70 | 0.413  | 0.421 |
| F2  | 6.30        | 6.50  | 0.248  | 0.256 |
| F3  | 2.10        | 2.30  | 0.083  | 0.091 |
| F4  | 5.70        | 5.90  | 0.224  | 0.232 |
| F5  | 5.66        | 5.86  | 0.223  | 0.231 |
| F6  | 1.10        | 1.30  | 0.043  | 0.051 |

|                                                                                                              |
|--------------------------------------------------------------------------------------------------------------|
| DOCUMENT NO.<br>Z8B00003328                                                                                  |
| SCALE<br>0 2.0 4mm                                                                                           |
| EUROPEAN PROJECTION<br> |
| ISSUE DATE<br>19-10-2007                                                                                     |
| REVISION<br>03                                                                                               |

PG-TO-251-3-1 (I-PAK), PG-TO-251-3-21 (I-PAK)



| DIM | MILLIMETERS |      | INCHES |       |
|-----|-------------|------|--------|-------|
|     | MIN         | MAX  | MIN    | MAX   |
| A   | 2.16        | 2.41 | 0.085  | 0.095 |
| A1  | 0.90        | 1.14 | 0.035  | 0.045 |
| b   | 0.64        | 0.89 | 0.025  | 0.035 |
| b2  | 0.65        | 1.15 | 0.026  | 0.045 |
| b4  | 4.95        | 5.50 | 0.195  | 0.217 |
| c   | 0.46        | 0.60 | 0.018  | 0.024 |
| c2  | 0.46        | 0.89 | 0.018  | 0.035 |
| D   | 5.97        | 6.22 | 0.235  | 0.245 |
| D1  | 5.04        | 5.77 | 0.198  | 0.227 |
| E   | 6.35        | 6.73 | 0.250  | 0.265 |
| E1  | 4.70        | 5.21 | 0.185  | 0.205 |
| e   | 2.29        |      | 0.090  |       |
| e1  | 4.57        |      | 0.180  |       |
| N   | 3           |      | 3      |       |
| L   | 8.89        | 9.65 | 0.350  | 0.380 |
| L1  | 1.90        | 2.29 | 0.075  | 0.090 |
| L2  | 0.89        | 1.37 | 0.035  | 0.054 |

|                                                                                                                     |
|---------------------------------------------------------------------------------------------------------------------|
| <b>DOCUMENT NO.</b><br>Z8B00003330                                                                                  |
| <b>SCALE</b><br>               |
| <b>EUROPEAN PROJECTION</b><br> |
| <b>ISSUE DATE</b><br>19-03-2008                                                                                     |
| <b>REVISION</b><br>03                                                                                               |

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